IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bounder bounder and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute						rials and N	ials and Mfg Information				
Supplie	Information															
Company name* Compar				npany unique ID			Unique ID Authority					Respor	Response Date*			
onsemi											2023-0	2023-06-06				
Contact N	ame	Title - Contact			1	Phone - Contact*					Email ·	Email - Contact*				
Product-I	Env-Stewards	Product Enviro Compliance				NA					Produ	Product-Env-Stewards@onsemi.com				
Authorize	d Representative*	Title - Representative			I	Phone - Representative*					Email -	Email - Representative*				
Product-I	Env-Stewards	Product Enviro Compliance				NA					Produ	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ffective Date Version Manufacturing		facturing Site	Weight*		*	UOM	Unit Type	
		6N137SDM 8PW 10MB T&R				2023-06-06 LITEONFG		ONFG		497.66		mg	Each			
Manufa	cturing Proccess Informa	tion						1		, 						
	Terminal Plating / Grid Array Ma	erminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Tem		Body Temper	perature Max Time at Peak		k Tempera	iture N	lumber o	f Reflow Cycl	es		
	Matte Tin (Sn) - annealed CU			U Alloy 1			260		C	3	30		nds 3	i		
Comments																
evel 1 - m	aximum time at peak temperatu	ire during sol	dering is 10-3	0 seconds												
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not orditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty r											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

omogeneous Material Weight Unit of		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.45	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.045	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.405	mg
Die	4.011	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.281	mg
			Supplier	Silicon (Si)	7440-21-3		3.73	mg
Die Attach	0.251	mg	Supplier	Silver (Ag)	7440-22-4		0.188	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.063	mg
Lead Frame	112.468	mg	Supplier	Silver (Ag)	7440-22-4		0.709	mg
			Supplier	Zinc (Zn)	7440-66-6		0.135	mg
			Supplier	Iron (Fe)	7439-89-6		2.59	mg
			Supplier	Copper (Cu)	7440-50-8		109	mg
			Supplier	Phosphorus (P)	7723-14-0		0.034	mg
Mold Compound-White	375.6	mg		Epoxy resin	proprietary data		50.706	mg
			Supplier	Phenol Resin	Proprietary Data		20.658	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		93.9	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		11.268	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		11.268	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		187.8	mg
Plating	2.88	mg	Supplier	Tin (Sn)	7440-31-5		2.88	mg
Wire Bond - Au	2.0	mg	Supplier	Gold (Au)	7440-57-5		2	mg